



General Description

The WSD30L65DN33 is the highest performance trench P-Channel MOSFET with extreme high cell density, which provide excellent $R_{\text{DS}(\text{ON})}$ and gate charge for most of the synchronous buck converter applications.

The WSD30L65DN33 meet the RoHS and Green Product requirement 100% E_{AS} guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

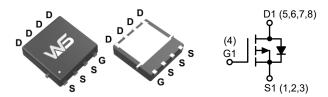
Product Summery

BVDSS	RDSON	ID
-30V	7.5mΩ	-50A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN3X3-8L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	-30	V	
V_{GS}	Gate-Source Voltage	±25	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-50	А	
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ -10V ¹	-20	А	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-11.9	А	
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ -10V ¹	-9.5	А	
I _{DM}	Pulsed Drain Current ²	-150	А	
E _{AS}	Single Pulse Avalanche Energy ³	54	mJ	
I _{AS}	I _{AS} Avalanche Current		А	
P _D @T _C =25°C	Total Power Dissipation ⁴	35.7	W	
P _D @T _A =25°C	Total Power Dissipation ⁴	2.08	W	
T _{STG}	Storage Temperature Range	-55 to 150	$^{\circ}$ C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-Ambient ¹		60	°C/W
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		40	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		3.5	°C/W



Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.0232		V/°C
	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-25A		7.5	9.5	mΩ
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-15A		12	17	
$V_{GS(th)}$	Gate Threshold Voltage	V -V I - 250··A	-1.3	-1.8	-2.3	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		4.6		mV/℃
,	Drain Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25℃			-1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =85°C			-30	
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		15		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		8		Ω
Q_{g}	Total Gate Charge (-4.5V)			23.2		
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-10V , I _D =-25A		7.5		nC
Q _{gd}	Gate-Drain Charge			12.7		
T _{d(on)}	Turn-On Delay Time			12	22	
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =6 Ω		13	23	
T _{d(off)}	Turn-Off Delay Time	I _D =-1A ,R _L =15Ω		62	112	ns
T _f	Fall Time			101	182	
C _{iss}	Input Capacitance			2240	2910	
C _{oss}	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		465		pF
C _{rss}	Reverse Transfer Capacitance			320		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V =V =0V Force Current			-50	Α
I _{DM}	Pulsed Source Current ^{2,6}	V _G =V _D =0V , Force Current			-150	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃		-0.8	-1.2	V
t _{rr}	Reverse Recovery Time	 IF=-25A,dI/dt=100A/μs, T _J =25℃		23		nS
Qrr	Reverse Recovery Charge	20/1,α//ατ 100/1/μο, 1		10		nC

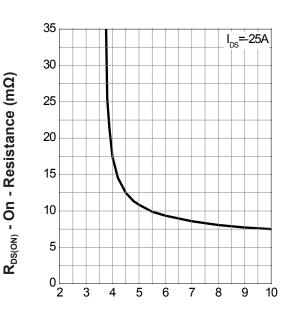
Note

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper, $t \le 10$ sec.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1 mH, I_{AS} =-33A
- 4. The power dissipation is limited by 150°C junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



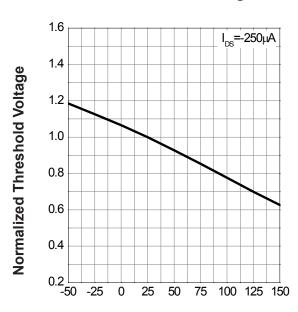
Typical Characteristics

Gate-Source On Resistance



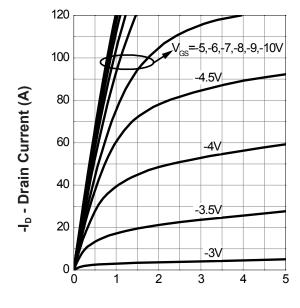
-V_{GS} - Gate - Source Voltage (V)

Gate Threshold Voltage



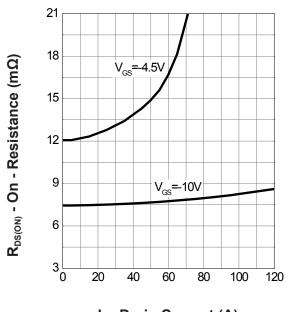
 T_j - Junction Temperature (°C)

Output Characteristics



-V_{DS} - Drain - Source Voltage (V)

Drain-Source On Resistance



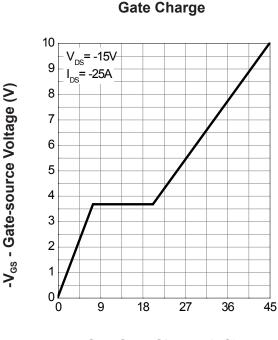
-I_D - Drain Current (A)



Typical Characteristics(Cont.)

Capacitance 3500 Frequency=1MHz 3000 2500 C - Capacitance (pF) Ciss 2000 1500 1000 Coss 500 0 [10 25 15 20 30

-V_{DS} - Drain-Source Voltage (V)



Q_G - Gate Charge (nC)

Fig.9 Normalized Maximum Transient Thermal Impedance

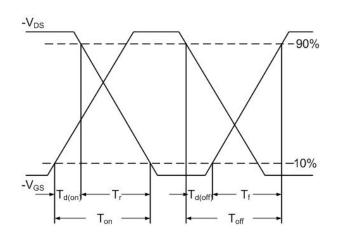


Fig.10 Switching Time Waveform

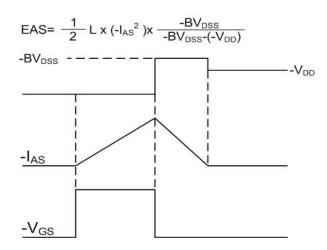
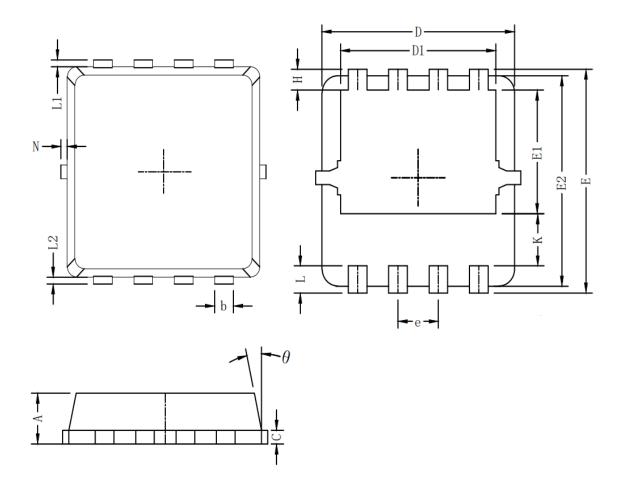


Fig.11 Unclamped Inductive Switching Waveform



Packaging information



Symbol	Dim in mm				
	min	typ	max		
А	0.6	0.75	0.9		
b	0.2	0.3	0.4		
С	0.15	0.2	0.25		
D	3	3.1	3.2		
D1	2.3	2.45	2.6		
E	3.15	3.3	3.45		
E1	1.43	1.73	1.93		
E2	2.9	3.05	3.2		
е	0.65BSC				
Н	0.2	0.35	0.5		
K	0.57	0.77	0.87		
L	0.3	0.4	0.5		
L1/L2	0.1REF				
θ	8°	10°	13°		
N	0		0.15		



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BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR
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